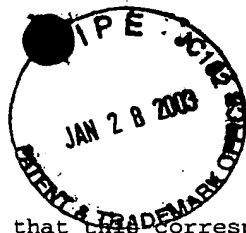


GR 00 P 1583

BOX AF



AF1700

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

By: h p ~

Date: 1/22/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Klaus Lowack et al.

Applic. No. : 09/817,963

Filed : March 27, 2001

Title : Method For The Metalization Of An Insulator
And/Or A Dielectric

Examiner : Brian K. Talbot

Group Art Unit : 1762

A M E N D M E N T under 37 C.F.R. § 1.116

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

TECHNOLOGY CENTER 1700

JAN 30 2003

RECEIVED

Sir :

Responsive to the final Office action dated October 22, 2002

kindly amend the above-identified application as follows:

In the Claims:

Claim 4 (amended). A process for metallizing at least one
insulating layer of an electronic or microelectronic component,
which comprises:

01